

## Parameter of flexible circuit boards in the Flex Pool

### Base material

Printed circuit boards in the Flex Pool are manufactured from Polyimide films.

The 1- or 2-layer flexible printed circuit boards have a material thickness of 0.2 mm.

The copper thickness amounts to 18 microns, the thickness of Polyimide to 50 microns.

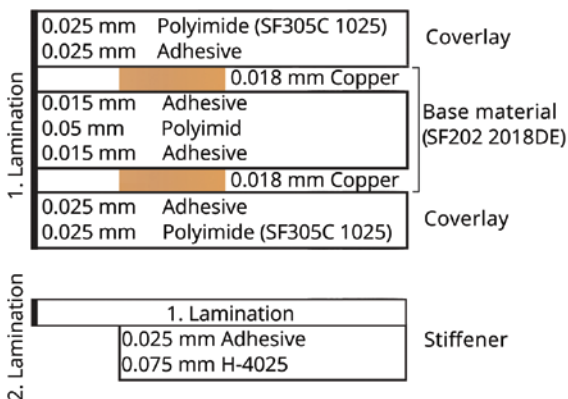
Property	Polyimide
Initial Tear Strength	500 g
Flexural strength	≥ 10000/cycle*
Copper adhesion	≥ 0,70 N/mm <sup>2</sup>
Dielectric Constant	≤ 3,7 (1,1 GHz)
Withstand solder bath (°C)	288°C (> 10 s)
Moisture absorption	≤ 3 %
Expansion	± 0,20 %

\* IPC-TM 650/2.4.3

### Layer Stackup Flex Pool

#### Layer: 2

Thickness: 0.2 mm without Stiffener



### Technical Parameters

Number of layers	1-2
Copper	Single-sided or double-sided
Surface	ENIG
Film material	Polyimide
Polyimide thickness	50 µm
Copper thickness	18 µm
Circuit board thickness	0.2 mm
Max. size of the circuit board	Length: 400 mm Width: 250 mm
Min. size of the circuit board	Length: 10 mm / Width: 10 mm
Flex cover film	Clearance: ≥ 200 µm
Min. conductor width / conductor clearance	125 µm
Vias	via diameter ≥ 200 µm
Min. via-via spacing	450 µm
Min. milling radius	100 µm
Min. copper-contour clearance	200 µm
Milling tolerance	+/- 100 µm
Silkscreen	both sides